

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	aluminum near2 thermal with expasion with epoxy	USPAT	OR	ON	2005/08/09 09:58
L2	0	aluminum near2 thermal with expasion	USPAT	OR	ON	2005/08/09 09:58
L3	4549	aluminum near2 thermal	USPAT	OR	ON	2005/08/09 10:04
L4	203	(wir\$2 with interconnection) with copper	USPAT	OR	ON	2005/08/09 10:05
S2	2353	(257/773).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 15:21
S3	41	S2 and heat with interconnect\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:21
S4	104	("3539705"   "3846166"   "4096623"   "4164461"   "4308090"   "4601915"   "4670091"   "4849070").PN. OR ("5117276"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 12:18
S5	11	("5117276"   "5444015"   "5798559"   "6245658"   "6255712"   "6277728"   "6386939"   "6403461"   "6614092").PN. OR ("6713835"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 12:20
S6	1339	S2 and line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:21
S7	343	S2 and line with (power signal)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 12:22
S8	9	("5814844"   "5874754"   "6091088"   "6114767"   "6133079"   "6177709"   "6288447"   "6320234"   "6326651").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 14:54
S9	9	dummy near interconnection with heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 12:42

S10	5	("5441915"   "5729047"   "5811352").PN. OR ("6717267").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 12:38
S11	9	dummy near interconnection same heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/07/21 12:42
S12	10	dummy near interconnection same heat	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 12:43
S13	1	S12 not S11	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 12:42
S14	36	dummy near interconnection and heat	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/07/21 12:43
S16	5	(US-20020058411-\$).did. or (US-6800883-\$ or US-6717267-\$ or US-6913990-\$ or US-6664642-\$).. did.	US-PGPUB; USPAT	OR	ON	2005/07/22 10:58
S17	51	interconnection with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 10:59
S18	610	(via damascene) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:00
S19	8	(damascene) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:00
S20	4	(via near4 dummy) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:03

S21	0	(interconnect near4 dummy) with heat adj transfer and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:04
S22	0	(interconnect near4 dummy) with heat adj transf\$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:04
S23	0	(interconect near4 dummy) with heat adj transf\$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:04
S24	0	(interconnecting near4 dummy) with heat adj transf\$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:04
S25	0	(pattern near4 dummy) with heat adj transf\$3 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:05
S26	0	(pattern near4 dummy) with heat adj transf\$4 and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:05
S27	9	(pattern near4 dummy) with heat near2 (transfer\$3 dissipat\$3 )and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:06
S28	9	(dummy near4 pattern) with heat near2 (transfer\$3 dissipat\$3 )and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:07

S29	1	(dummy near interconnect\$3) with heat near2 (transfer\$3 dissipat\$3 )and (IC integrated adj circuit chip die wafer semiconductor silicon).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 11:07
S30	2	(dummy near interconnect\$3) with heat near2 (transfer\$3 dissipat\$3 )and (IC integrated adj circuit chip die wafer semiconductor silicon). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 13:23
S31	393	epoxy with phenolic with curing adj accelerator with inorganic adj filler	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/22 13:32
S32	75864	heat with dissipation	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:24
S33	4157080	(semiconductor ic integrated adj circuit die chip wafer silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:22
S34	167541	power near2 line	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:22
S35	208	interconnect with S32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:23
S36	182	S35 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:23

S37	13	S36 and S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:23
S38	5533	heat with interconnect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:24
S39	2616	S38 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:25
S40	138	S39 and S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:27
S41	208622	heat with (wir\$3 via damascene trench)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:28
S42	69890	S41 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:28
S43	4074	S41 with S32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:29
S44	2355	S43 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:29

S45	96	S44 and S34	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:31
S46	31	S45 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:34
S47	53643	(257/7\$2).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 15:36
S48	8382	(257/69\$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 15:36
S50	57940	S47 S48	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:36
S51	10061	S50 and heat with (dissipat\$3 remov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:39
S52	8692	S50 and heat near2 (dissipat\$3 remov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:37
S53	5275049	S52 and heat (interconnection via plug wir\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:38

S54	405899	heat with (dissipat\$3 remov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:40
S55	5272660	(interconnection via plug wir\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:39
S56	24126	S54 with S55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:41
S57	1697	S50 and S56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:40
S58	228800	heat near2 (dissipat\$3 remov\$5)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:41
S59	13478	S58 with S55	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:44
S60	1353	S59 and S47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:42
S61	878	S59 and S47	USPAT	OR	ON	2005/08/08 15:43
S62	2306	(257/774).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 15:43

S63	45	S59 and S62	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:46
S64	3369	(257/758).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 15:46
S65	30	S59 and S64	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:51
S66	4	("5698897"   "5792677").PN. OR ("6242807").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 15:51
S67	786	(257/760).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 15:51
S68	3	S59 and S67	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:52
S69	353	(257/761).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 15:52
S70	3	S59 and S68	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:52
S71	4954	(257/76\$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/08 15:52

S72	17	S59 and S71	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/08 15:53
S73	9	("5700735"   "5736791"   "5739587"   "5891799"   "5923088"   "6028367"   "6143396"   "6180511"   "6251781").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 15:54
S74	6	("6028367").URPN.	USPAT	OR	ON	2005/08/08 15:54
S75	12	("5248903"   "5404047"   "5736791"   "5739587"   "5923088"   "5959356").PN. OR ("6028367").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 15:55
S76	12	("5248903"   "5404047"   "5736791"   "5739587"   "5923088"   "5959356").PN. OR ("6028367").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 15:59
S77	3	("5354717" "6018193" "20020061614").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 16:01
S78	2	S77 and heat	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 16:54
S79	1	"6717267".pn. and power	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 17:52
S80	460	double with heat with sink	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 18:36
S81	193	S80 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/08 18:37
S82	144	S80 and "257"/\$.ccls.	USPAT	OR	ON	2005/08/08 18:38
S83	56	S82 and wire	USPAT	OR	ON	2005/08/08 18:43
S84	138	andujar.xa.	USPAT	OR	ON	2005/08/09 09:57